SSOP

Shrink Small Outline Package

DESCRIPTION

Lingsen SSOP is a lead frame based plastic package with different body width of 150mil, 209mil and 300mil. It is available in different pin counts from 8L to 48L. SSOP packages are ideal for packaging Logic, Memory and Analog products in consumer and portable electronic applications.

The package meets JEDEC Moisture Sensitivity Level 3 standard that ensures reliability in its functions.

SPECIFICATIONS

• Die Thickness	
With down-set	457um (18mils) maximum
Without down-set	304um (12mils) maximum
• Gold Wire	99.99% Au
• Mold Compound	EME G600 (Green)
	EME 6600CSP (Non-Green)
• Plating	Matte Tin
• Marking	White Ink / Laser Mark
• Packing	Antistatic Tube

APPLICATIONS

- Amplifiers, Controllers
- Logic, Linear, Analog, Memory
- Consumer products: Pagers,
- Portable Devices
- RF devices / Components

RELIABILITY

MSL Level: MSL 3 @ 240°C for Sn/Pb

MSL Level: MSL 3 @ 260°C for Pb-Free & Green

Pressure Cook Test: 168hrs (121°C, 100%RH, 2atm)

Temperature Cycling: 500cycles (-65°C/+150°C)

HAST: 100hrs (130°C, 85%RH)

Temperature & Humidity Test: 1,000hrs (85°C, 85%RH)

High Temperature Storage: 1,000hrs (150°C)

FEATURES

- Available pin count from 8L to 48L
- Ink/Laser marking available
- Gull wing lead format
- JEDEC standard compliant
- JEDEC MSL level 3 qualified for all pin counts

THERMAL PERFORMANCE

Package	Body Size (mm)	Pad Size (mm)	Die Size (mm)	Thermal Performance θja (°C/W)
SSOP 16L	3.91x4.8514	2.286x2.286	1.595x1.605	71.96
SSOP 48L	7.49x15.88	3.81x3.81	1.68x1.64	49.65

Note: Simulated with JEDEC Standard 4-layer test board under still air condition, ambient temperature 45°C

ELECTRICAL PERFORMANCE

Package	Body Size (mm)	Pad Size (mm)	Frequency (MHz)	Self Inductance (nH)	Self Capacitance (pF)	Resistance (mohm)
SSOP 16L	3.91x4.8514	2.286x2.286	100	2.011~2.718	0.358~0.439	134.4~203.6
SSOP 48L	7.49x15.88	3.81x3.81	100	3.46~7.304	0.563~1.195	122.9~250.9

Note: Results are simulated. Data is available through 2.5GHz.

CROSS-SECTION